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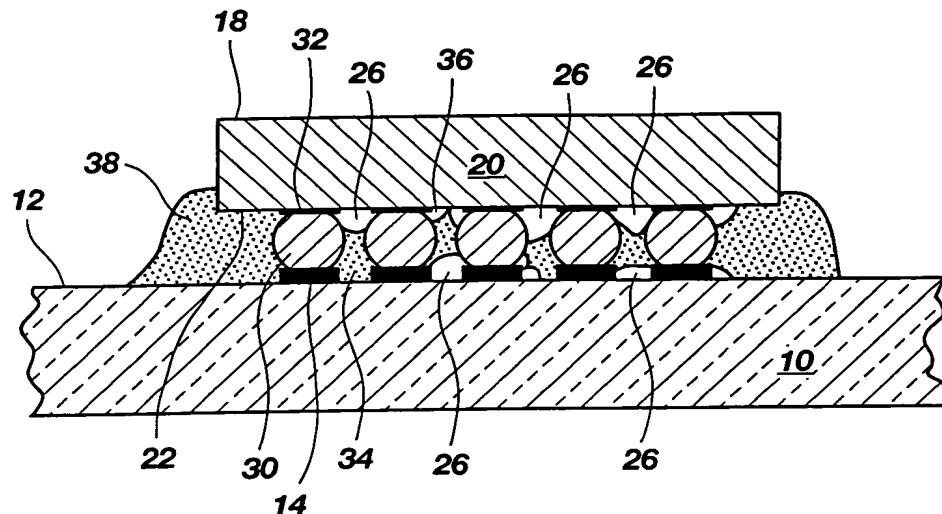


Fig. 1
(PRIOR ART)

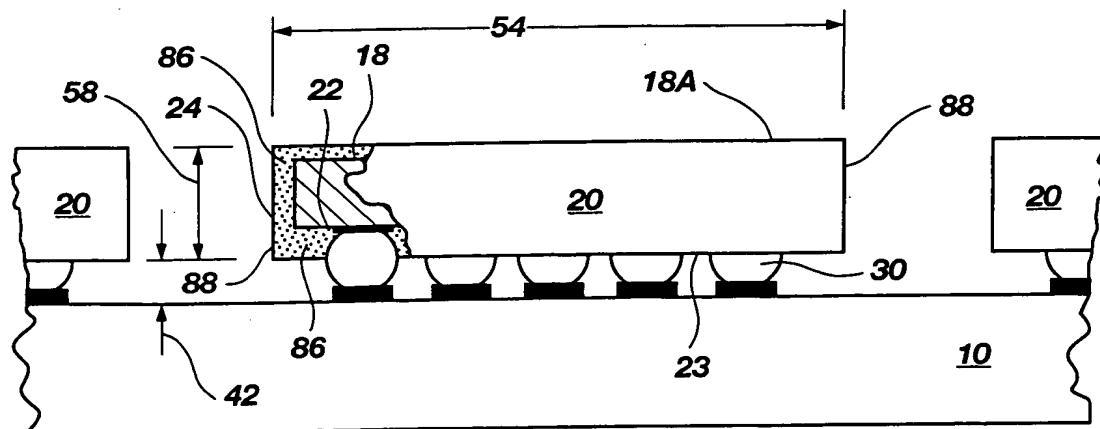
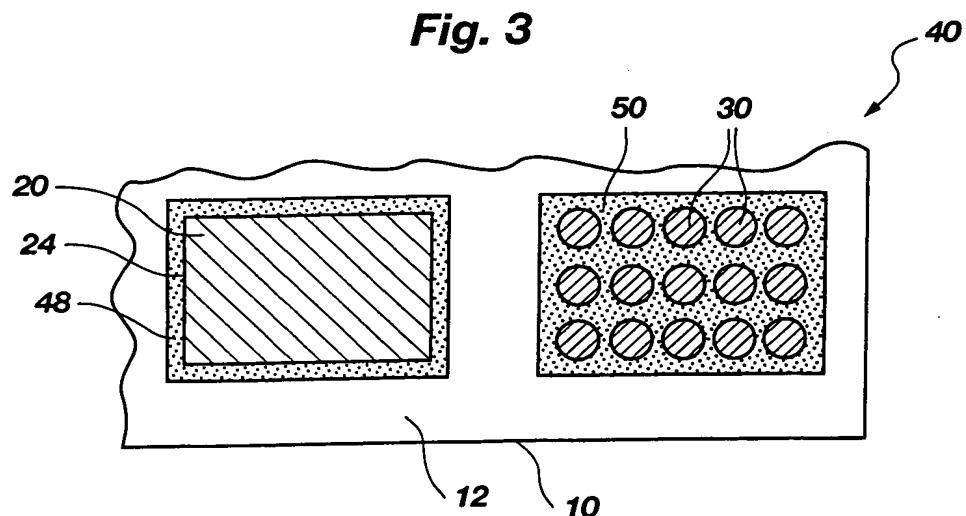
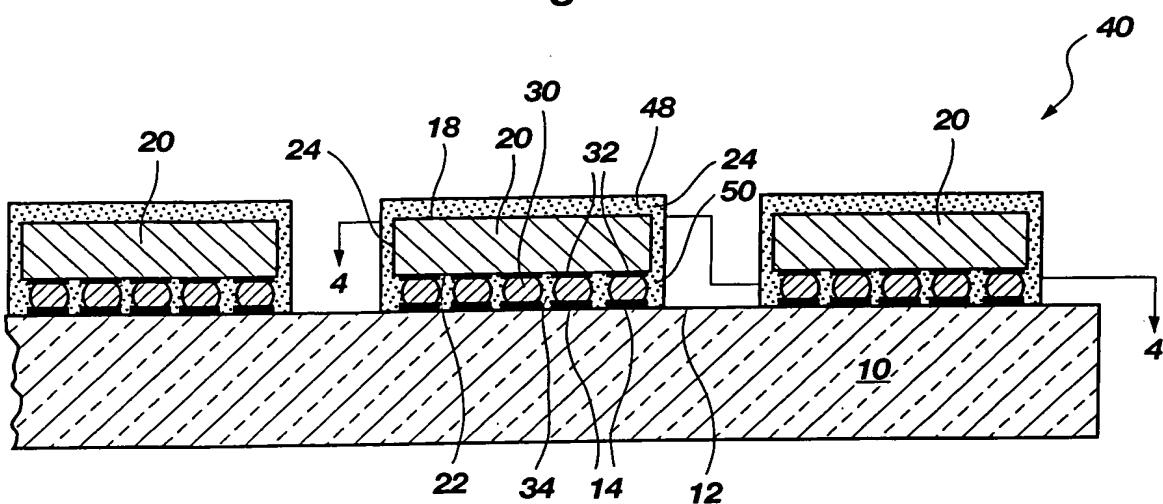
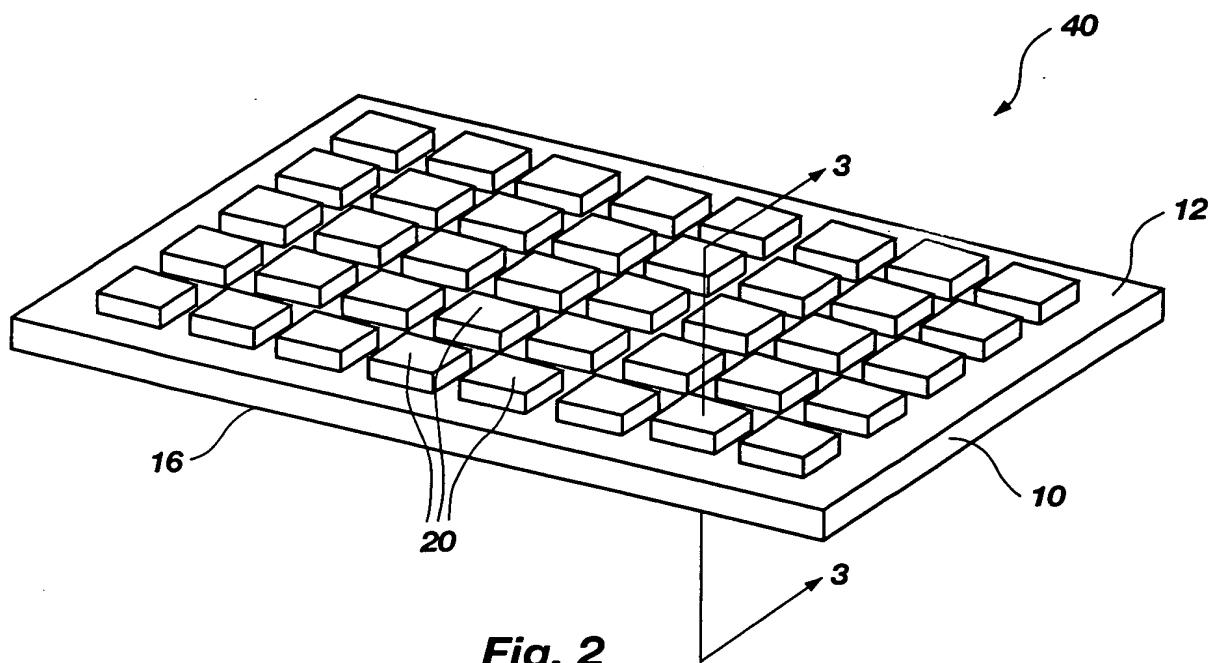


Fig. 5A

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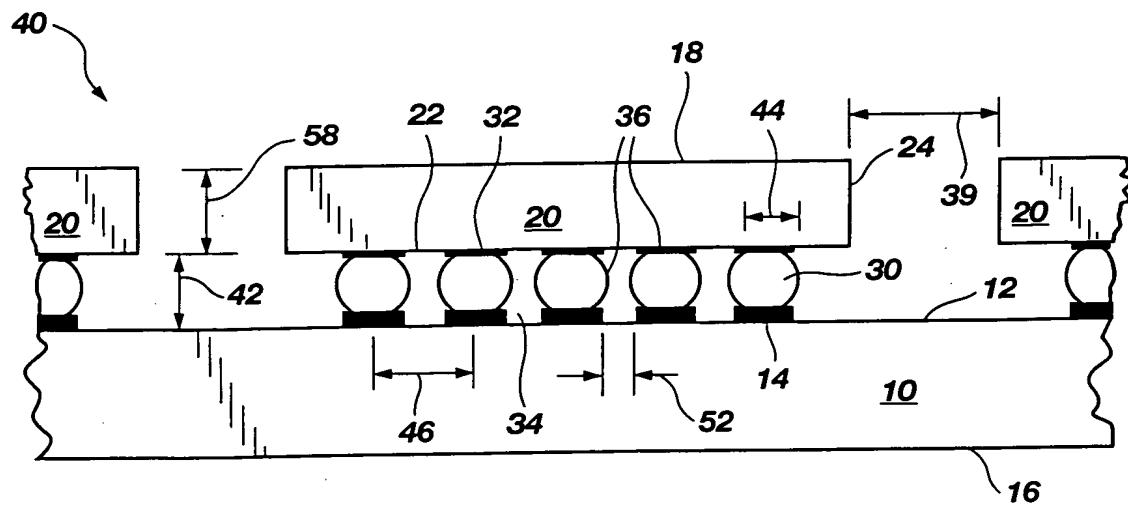


Fig. 5

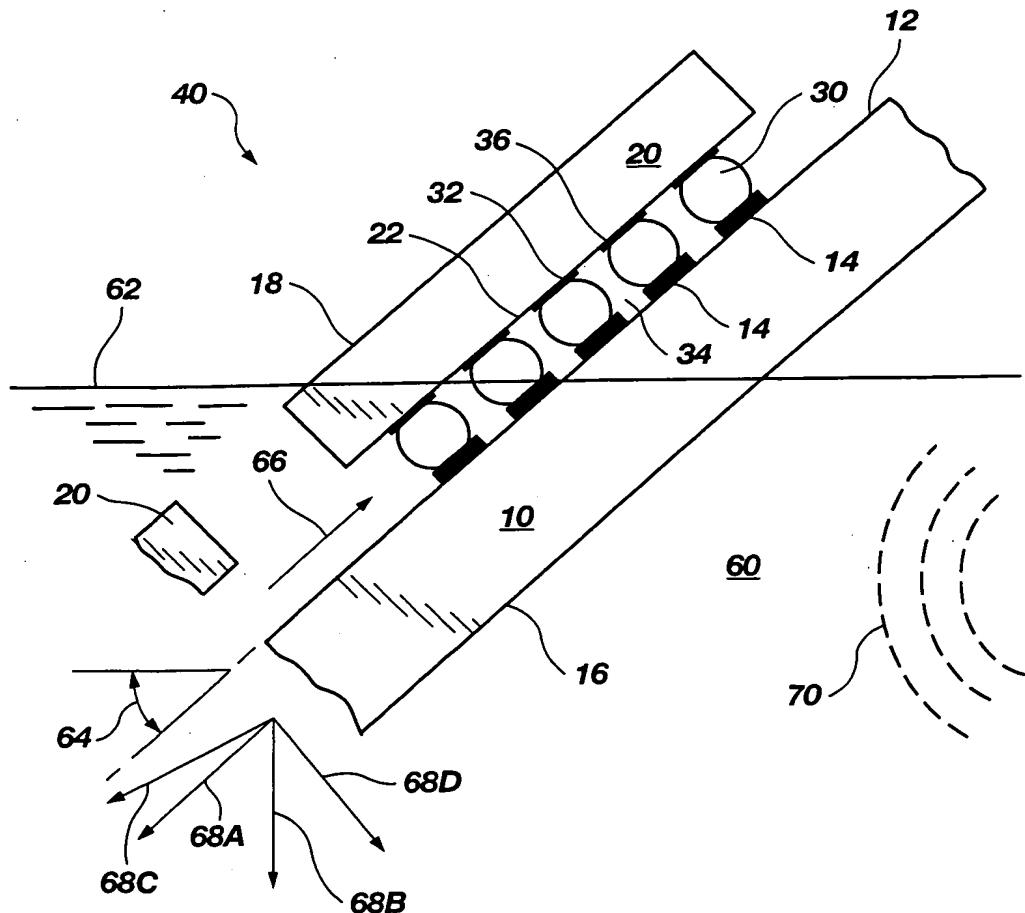


Fig. 6

**TITLE: UNDERFILL AND ENCAPSULATION OF CARRIER
SUBSTRATE-MOUNTED FLIP-CHIP COMPONENTS USING
STEREOLITHOGRAPHY**

Inventor: Warren M. Farnsworth
Docket No.: 2269-3924-3US

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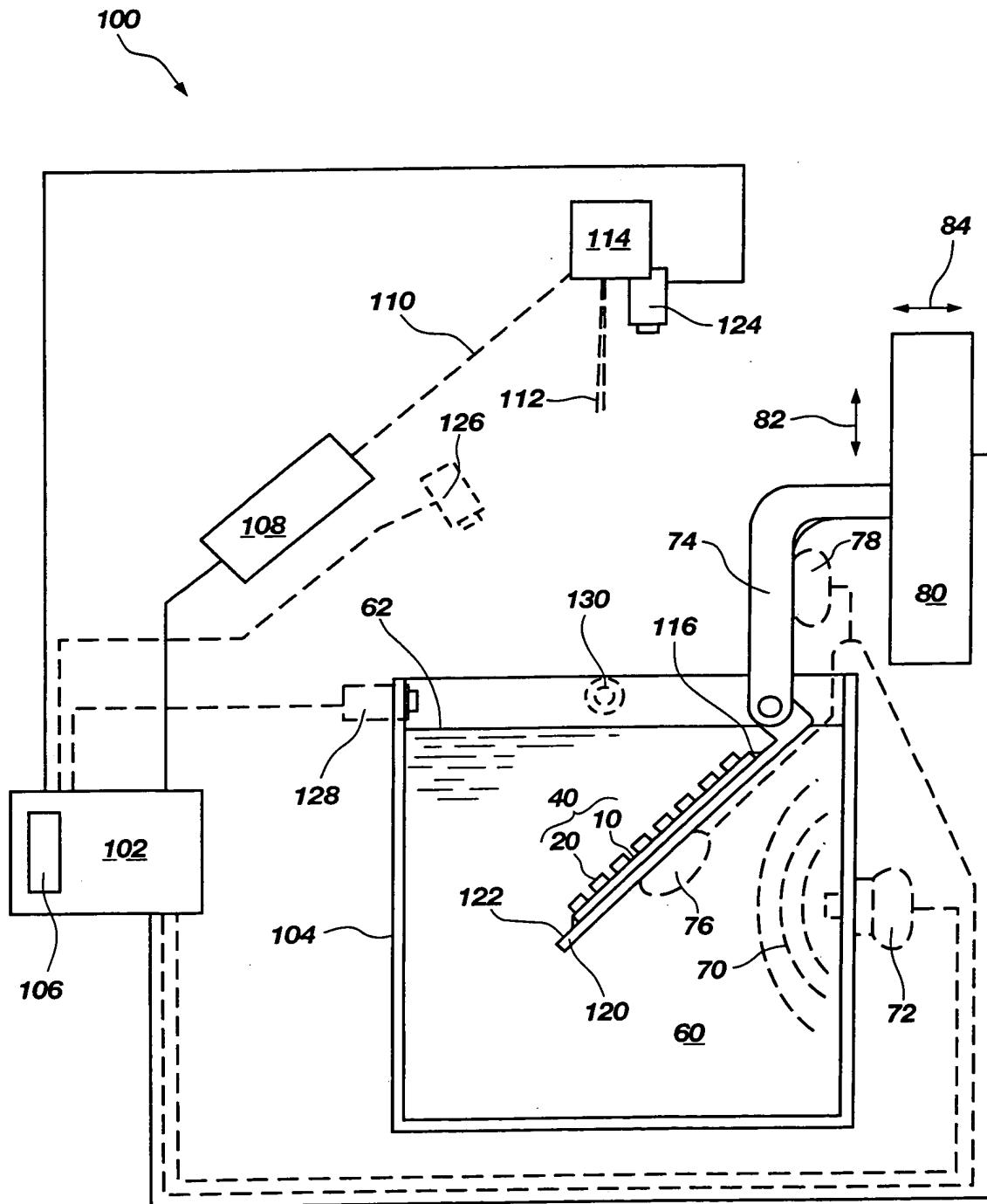


Fig. 7

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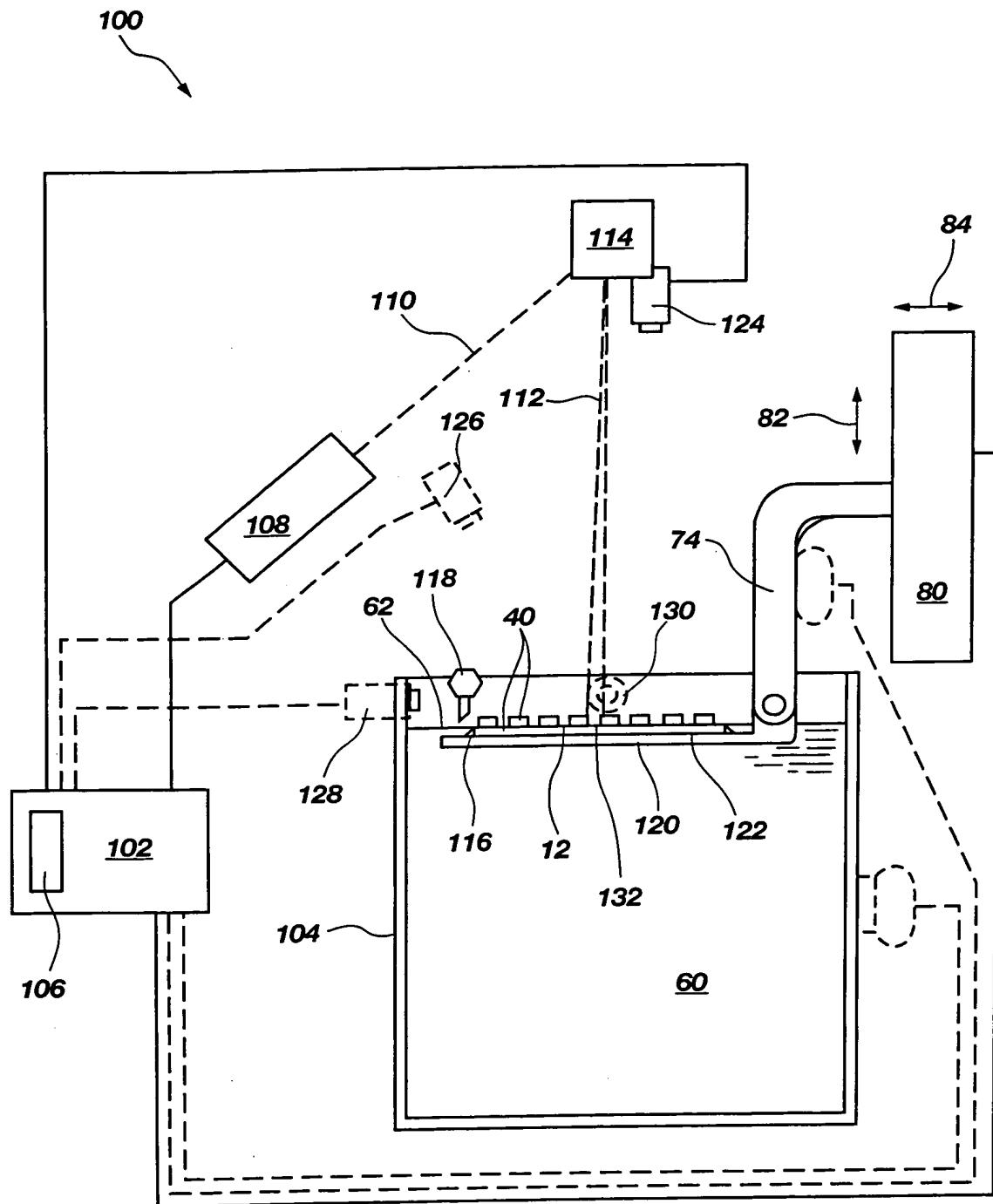


Fig. 8

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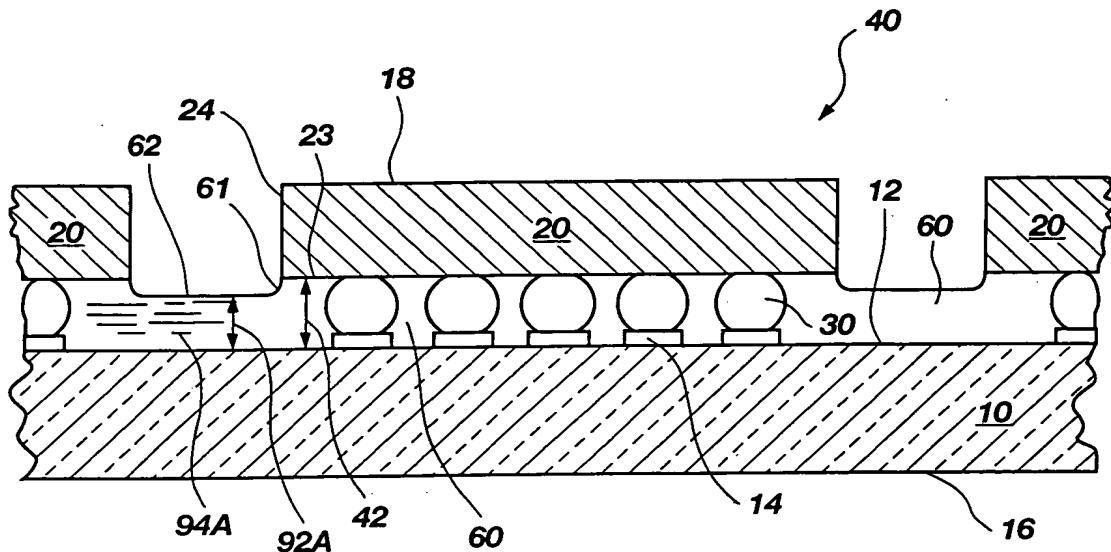


Fig. 9

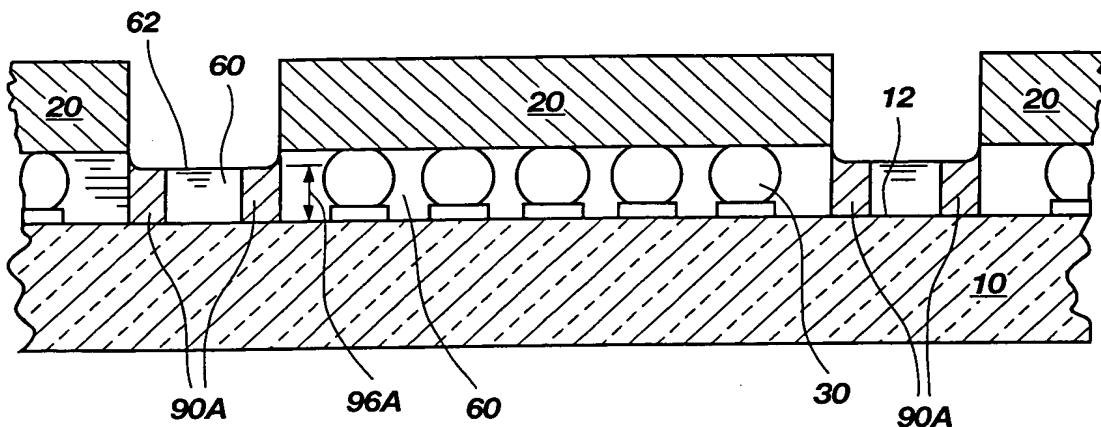


Fig. 10

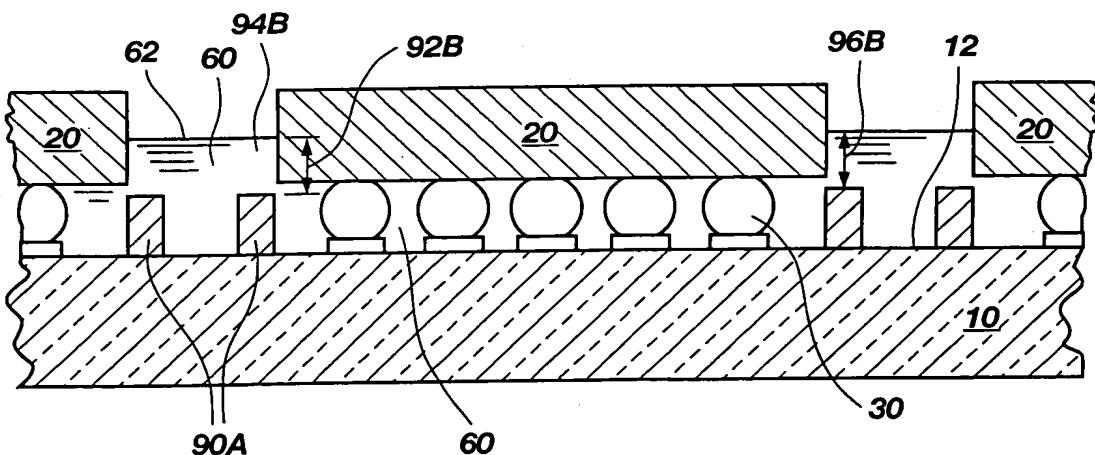


Fig. 11

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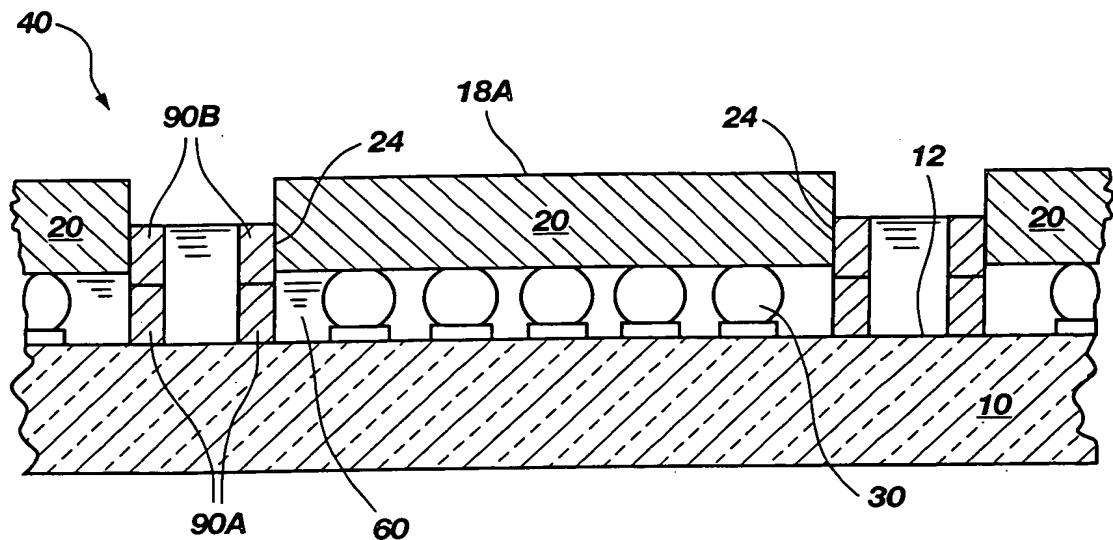


Fig. 12

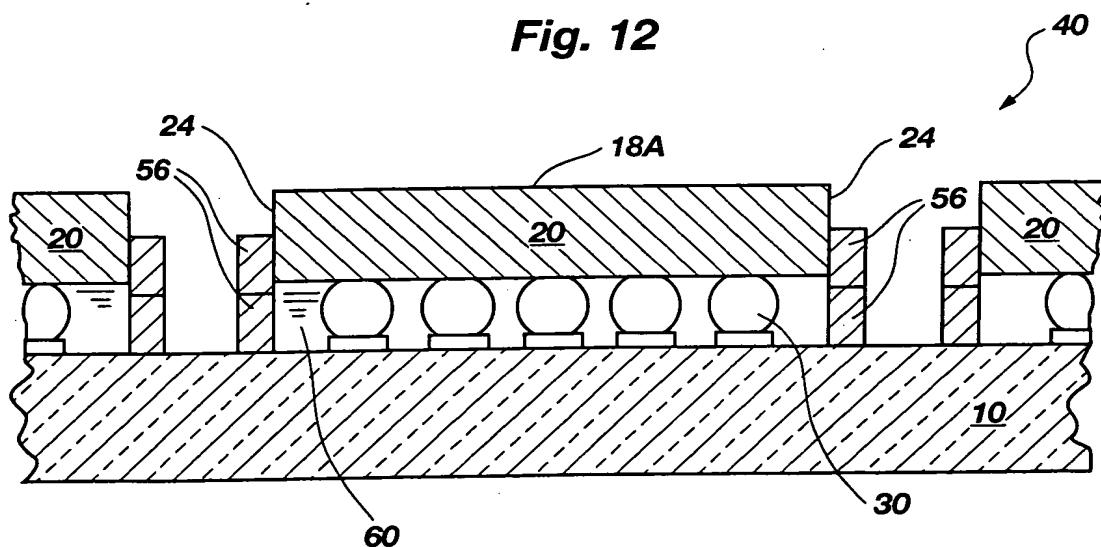


Fig. 13

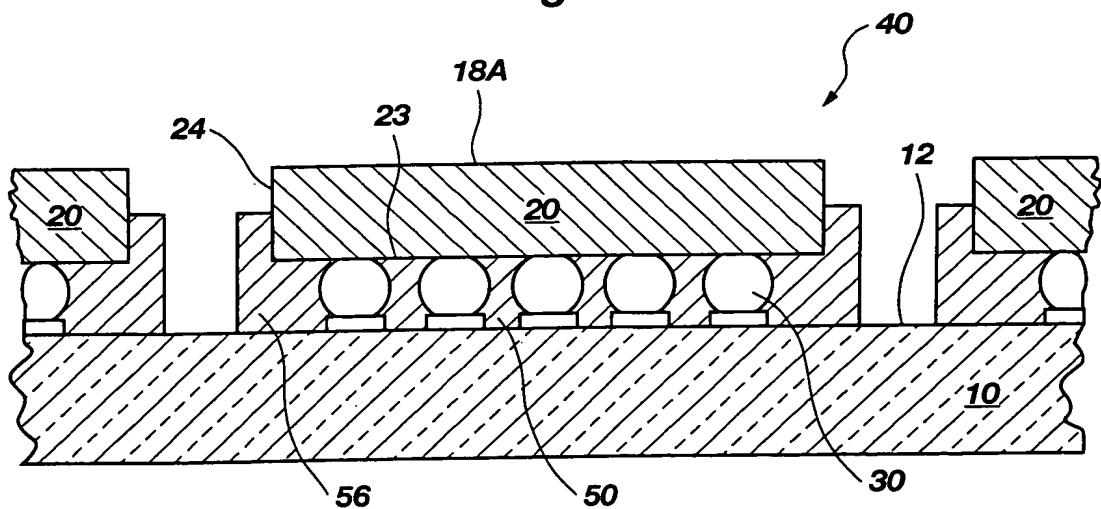


Fig. 14

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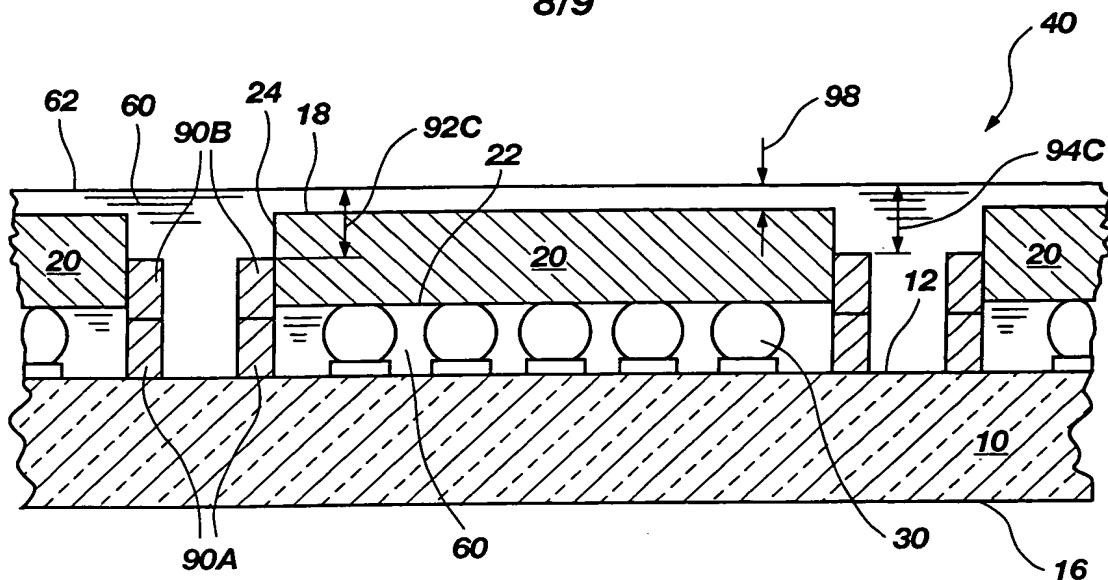


Fig. 15

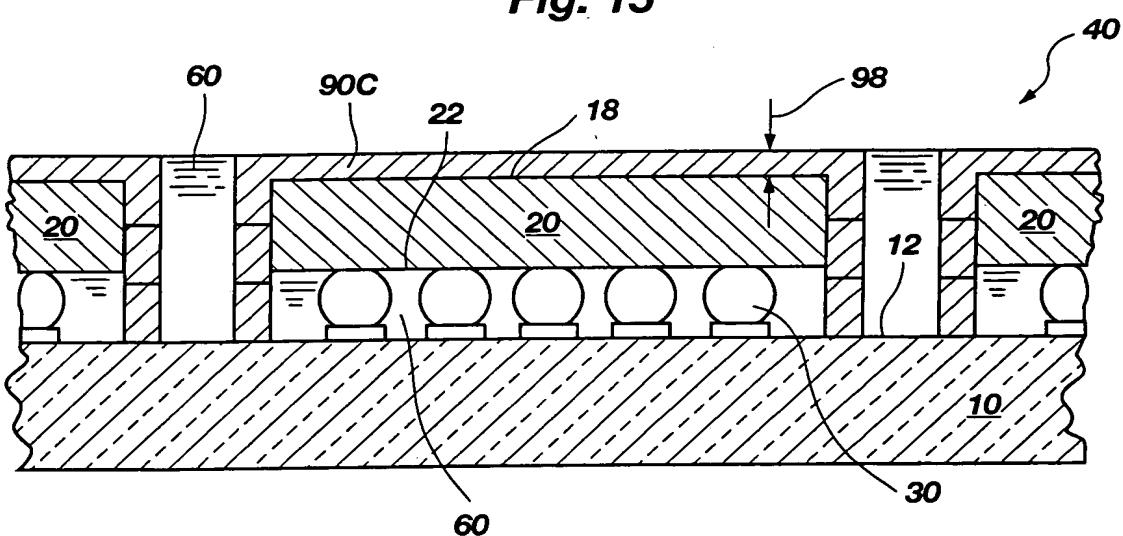


Fig. 16

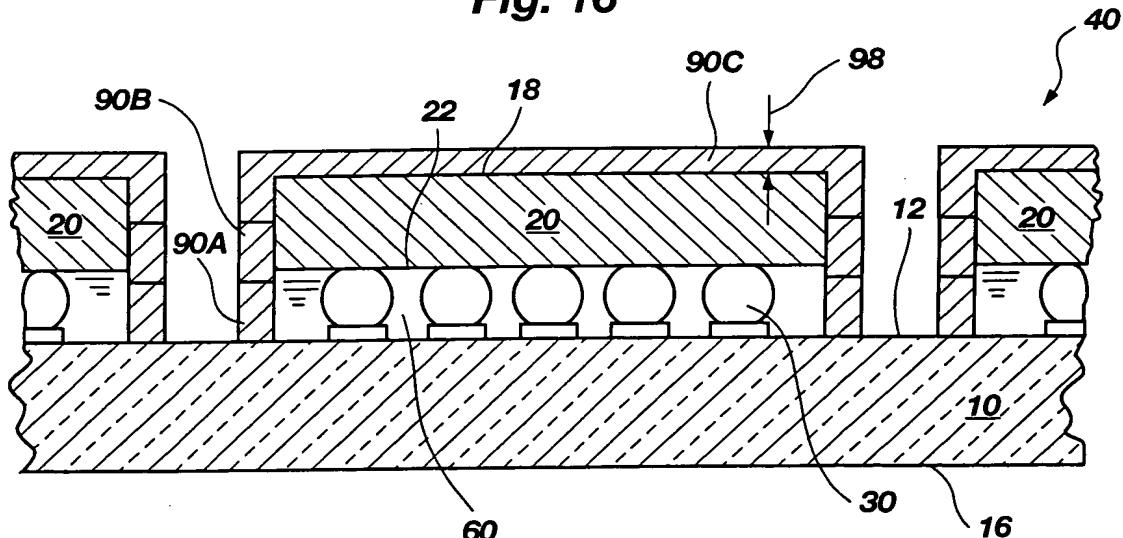


Fig. 17

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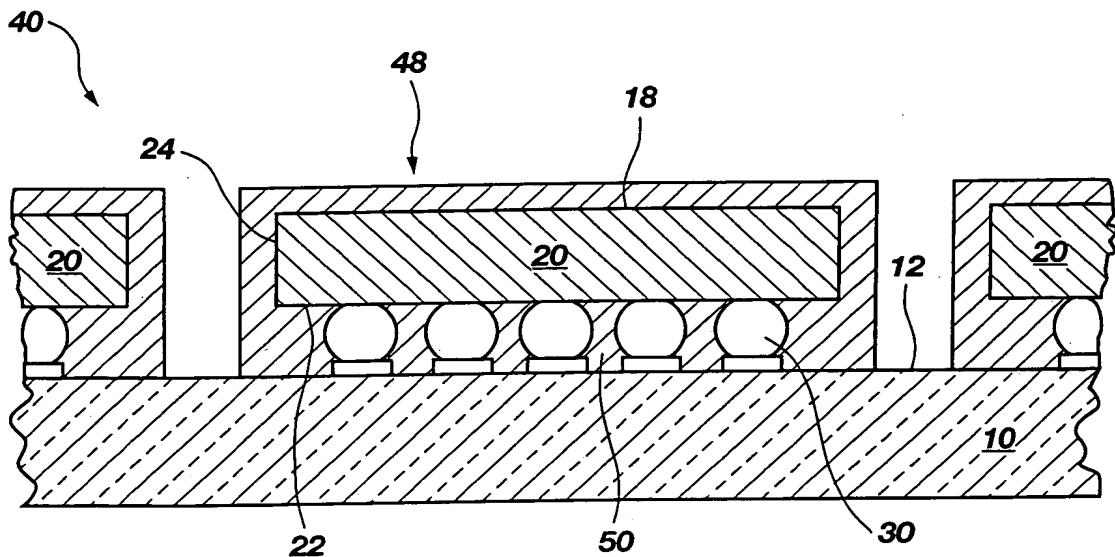


Fig. 18